



## 600V Super-Junction Power MOSFET

### FEATURES

- Very low FOM  $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- RoHS compliant



### APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information				
Device	TPA60R160M	TPP60R160M	TPV60R160M	TPW60R160M
Package	TO-220F	TO-220	TO-3PN	TO-247
Marking	60R160M	60R160M	60R160M	60R160M

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Value				Unit
		TO-220	TO-3PN	TO-247	TO-220F	
Drain-Source Voltage ( $V_{GS} = 0\text{V}$ )	$V_{DSS}$	600				V
Continuous Drain Current $T_C = 25^\circ\text{C}$	$I_D$	20				A
		12				
Pulsed Drain Current (note1)	$I_{DM}$	60				A
Gate-Source Voltage	$V_{GSS}$	$\pm 30$				V
Single Pulse Avalanche Energy (note2)	$E_{AS}$	418				mJ
Avalanche Current (note1)	$I_{AR}$	3.4				A
Repetitive Avalanche Energy (note1)	$E_{AR}$	0.63				mJ
MOSFET dv/dt ruggedness, $V_{DS} = 0\text{...}480\text{V}$	dv/dt	50				
Reverse diode dv/dt, $V_{DS} = 0\text{...}480\text{V}$ , $I_{SD} \leq I_D$	dv/dt	15				
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	151		34		W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~+150				°C

Parameter	Symbol	Value				Unit
		TO-220	TO-3PN	TO-247	TO-220F	
Thermal Resistance, Junction-to-Case	$R_{thJC}$	0.83			3.7	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	62			80	

**Specifications**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	600	--	--	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
		$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 150^\circ\text{C}$	--	--	100	
Gate-Source Leakage	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 30\text{V}$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.5	--	4.0	V
Drain-Source On-Resistance (Note3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$	--	0.14	0.16	$\Omega$
Gate resistance	$R_G$	f = 1.0MHz open drain	--	12	--	$\Omega$
<b>Dynamic</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 100\text{V}, f = 1.0\text{MHz}$	--	1726	--	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		--	71	--	
Reverse Transfer Capacitance	$C_{\text{rss}}$		--	5	--	
Total Gate Charge	$Q_g$	$V_{\text{DD}} = 480\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$	--	38	--	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		--	8	--	
Gate-Drain Charge	$Q_{\text{gd}}$		--	14.5	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 20\text{A}, R_G = 25\Omega$	--	31	--	$\text{ns}$
Turn-on Rise Time	$t_r$		--	69	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	124	--	
Turn-off Fall Time	$t_f$		--	48	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	20	$\text{A}$
Pulsed Diode Forward Current	$I_{\text{SM}}$		--	--	60	
Body Diode Voltage	$V_{\text{SD}}$	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 20\text{A}, V_{\text{GS}} = 0\text{V}$	--	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R = 400\text{V}, I_F = I_S, dI_F/dt = 100\text{A}/\mu\text{s}$	--	460	--	$\text{ns}$
Reverse Recovery Charge	$Q_{\text{rr}}$		--	5.5	--	
Peak Reverse Recovery Current	$I_{\text{rrm}}$		--	24	--	

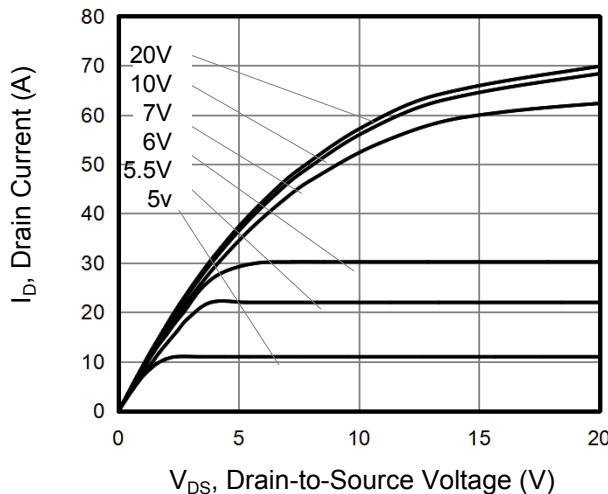
**Notes**

1. Repetitive Rating: Pulse Width limited by maximum junction temperature
2.  $I_{AS} = 3.4\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$

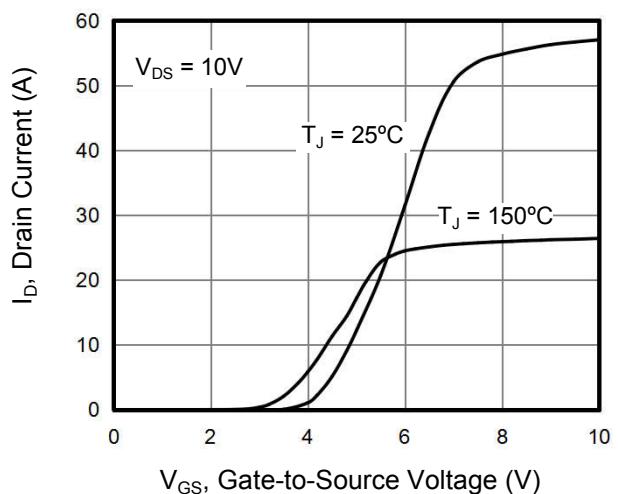


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

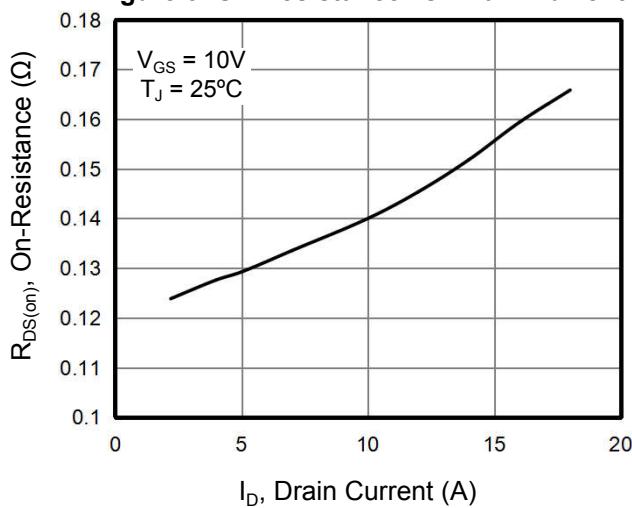
**Figure 1. Output Characteristics**



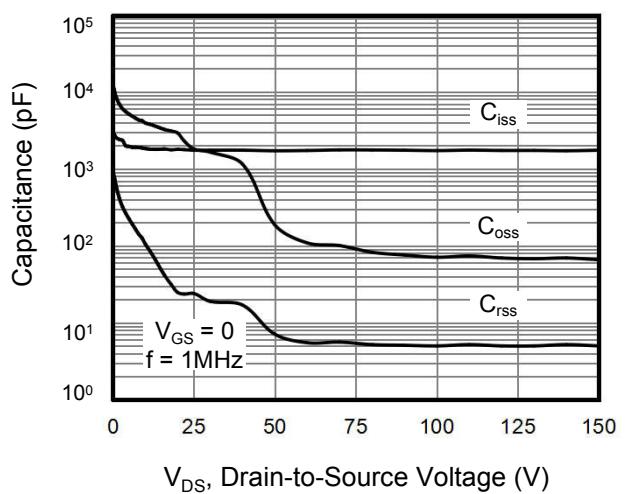
**Figure 2. Transfer Characteristics**



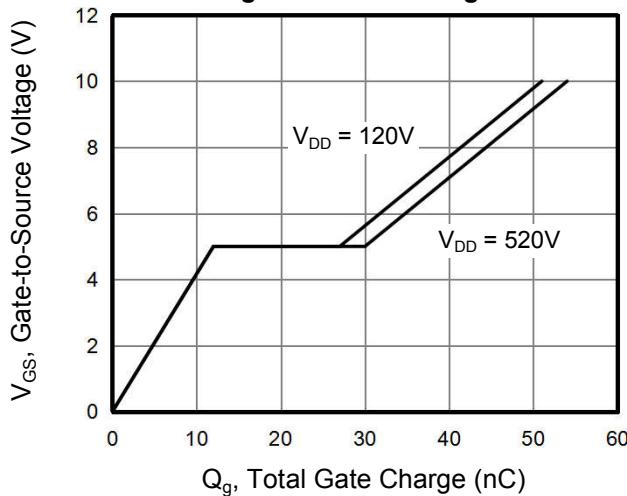
**Figure 3. On-Resistance vs. Drain Current**



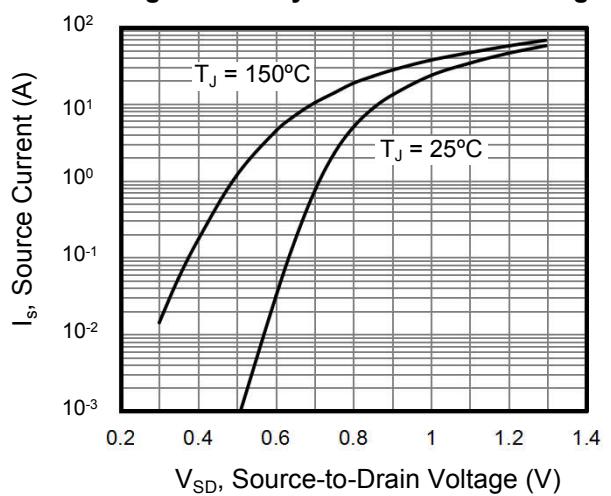
**Figure 4. Capacitance**



**Figure 5. Gate Charge**



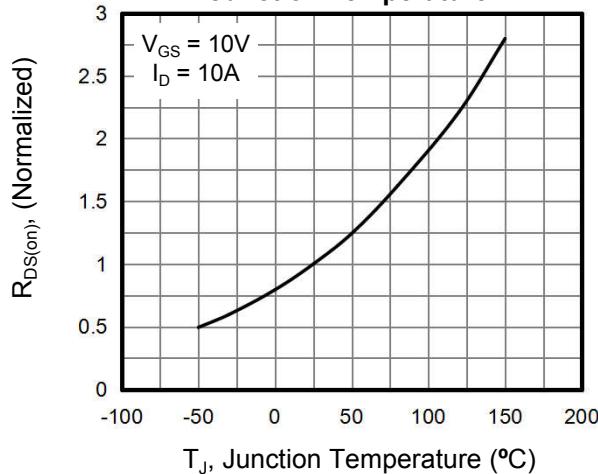
**Figure 6. Body Diode Forward Voltage**



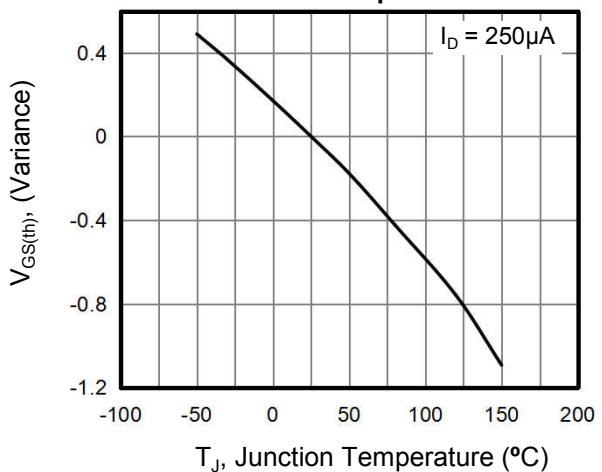


**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted

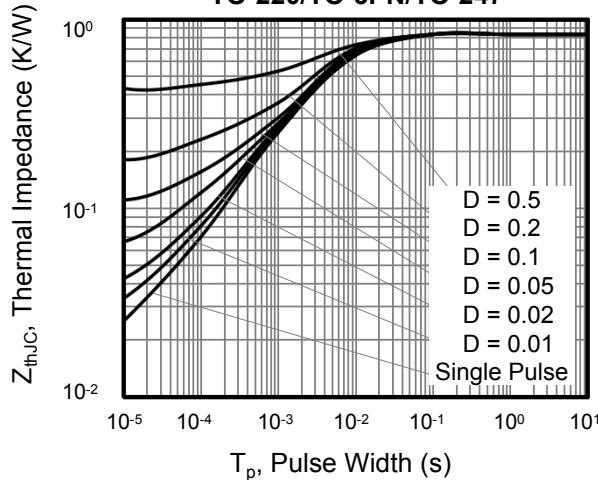
**Figure 7. On-Resistance vs. Junction Temperature**



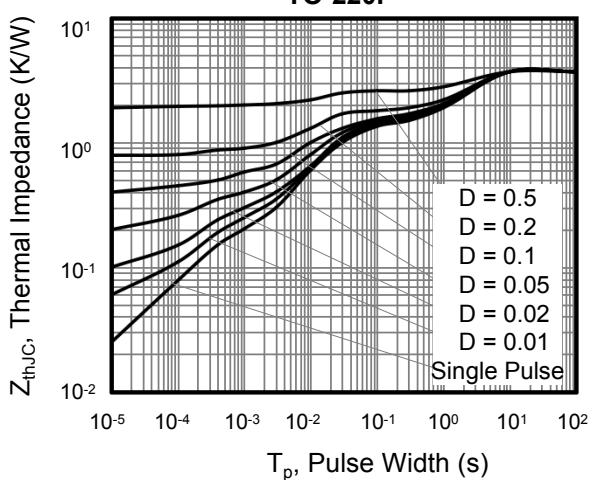
**Figure 8. Threshold Voltage vs. Junction Temperature**



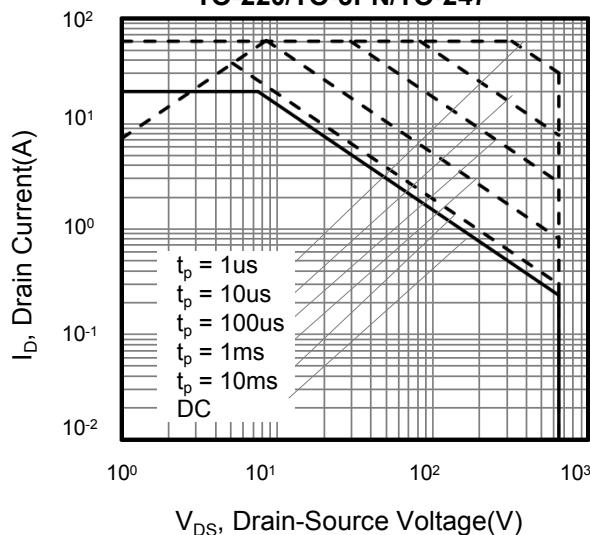
**Figure 9. Transient Thermal Impedance TO-220/TO-3PN/TO-247**



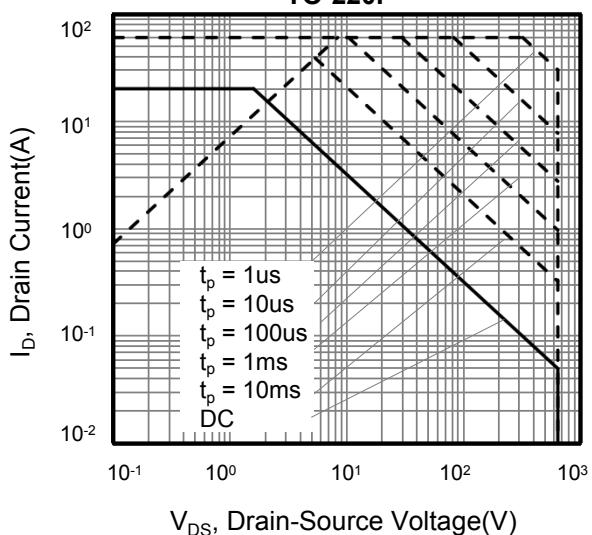
**Figure 10. Transient Thermal Impedance TO-220F**

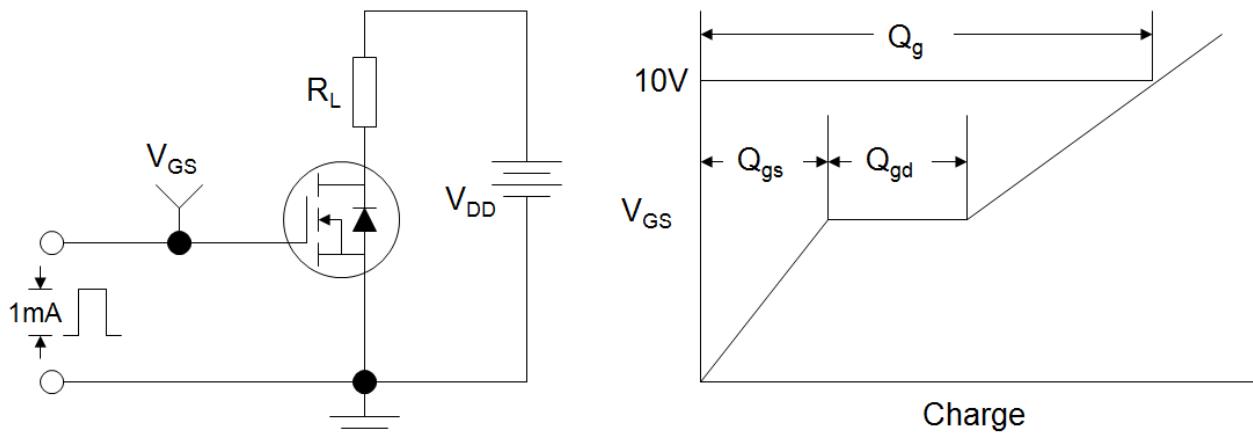
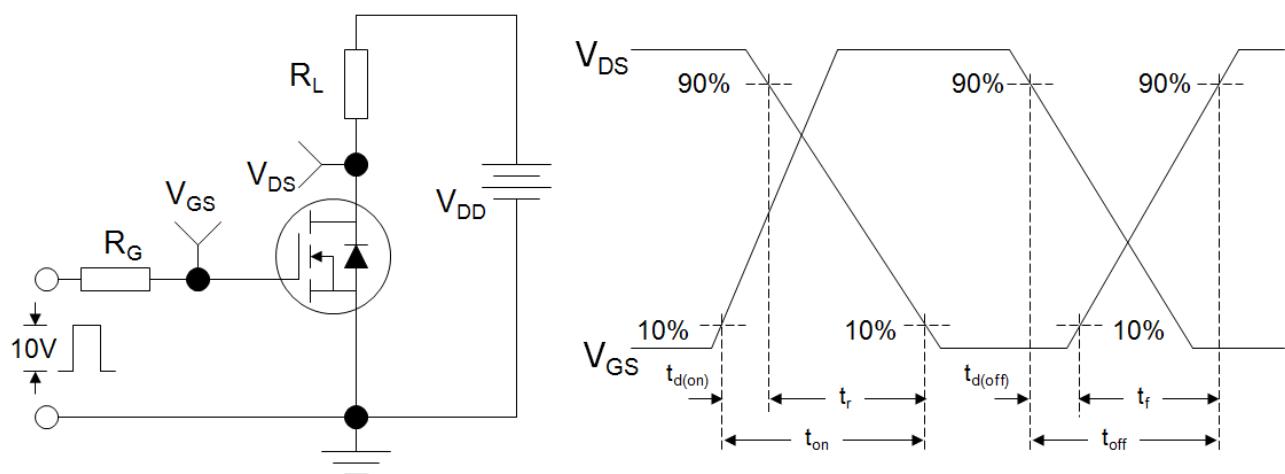
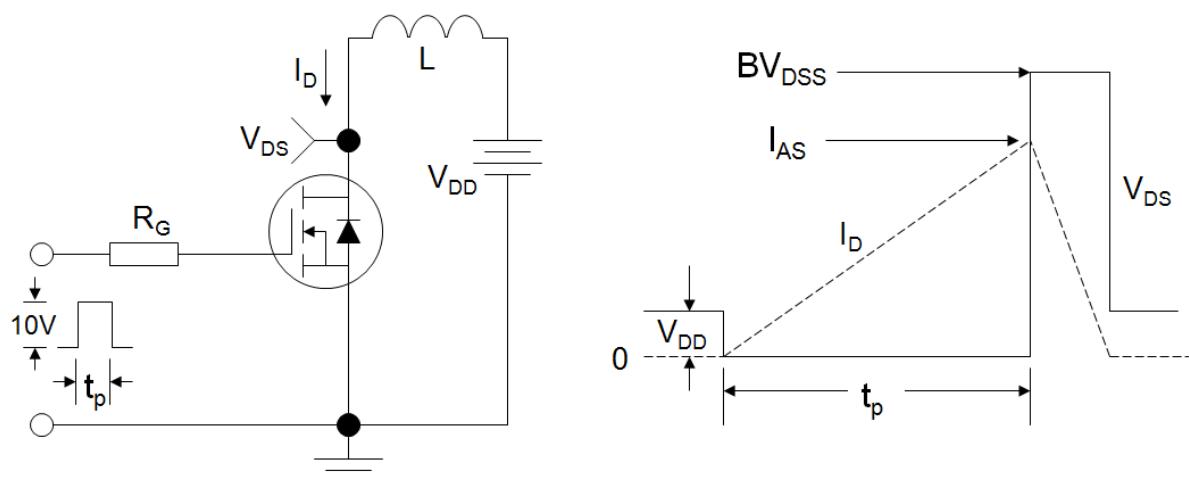


**Figure 12. Safe operation area for TO-220/TO-3PN/TO-247**



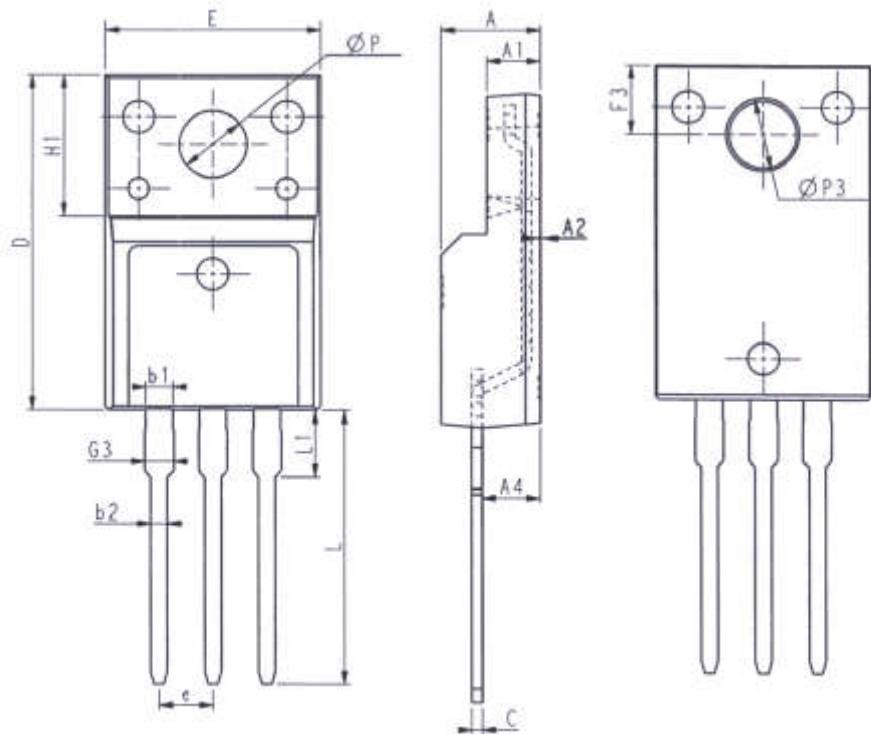
**Figure 13. Safe operation area for TO-220F**



**Figure A: Gate Charge Test Circuit and Waveform**

**Figure B: Resistive Switching Test Circuit and Waveform**

**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**




## TO-220F

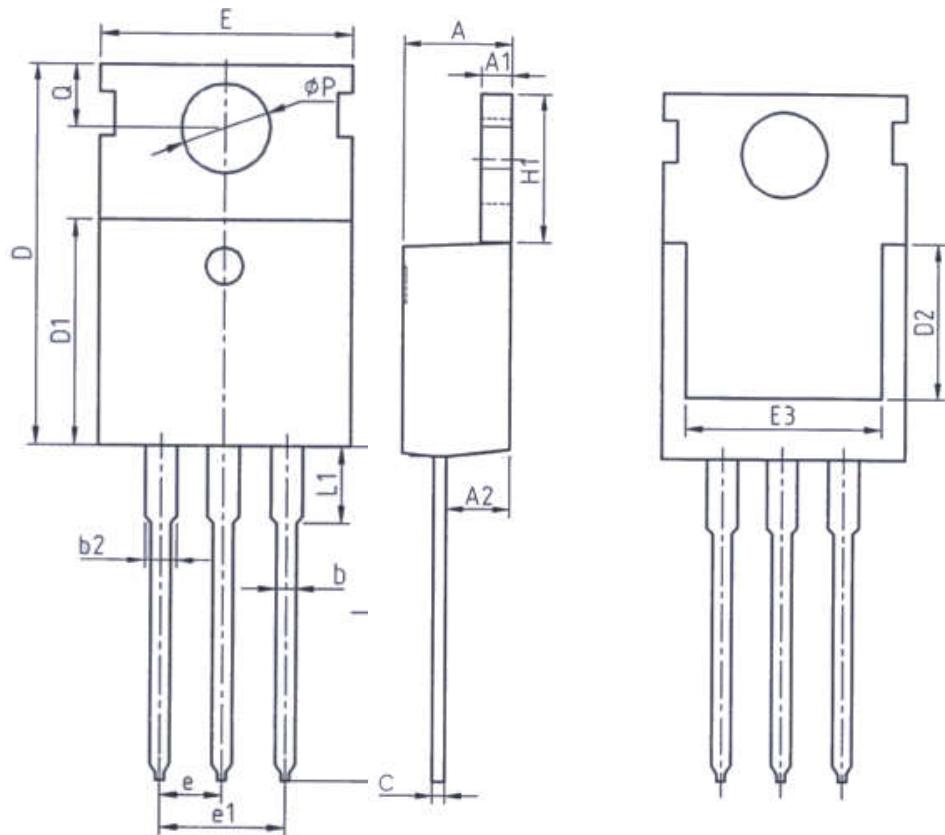


Unit: mm		
Symbol	Min.	Max.
E	9.96	10.36
A	4.50	4.90
A1	2.34	2.74
A2	0.30	0.60
A4	2.56	2.96
c	0.40	0.65
D	15.57	16.17
H1	6.70REF	
e	2.54BSC	

Unit: mm		
Symbol	Min.	Max.
L	12.68	13.28
L1	2.93	3.13
P	3.03	3.38
P3	3.15	3.65
F3	3.15	3.45
G3	1.25	1.55
b1	1.18	1.43
b2	0.70	0.95



## TO-220

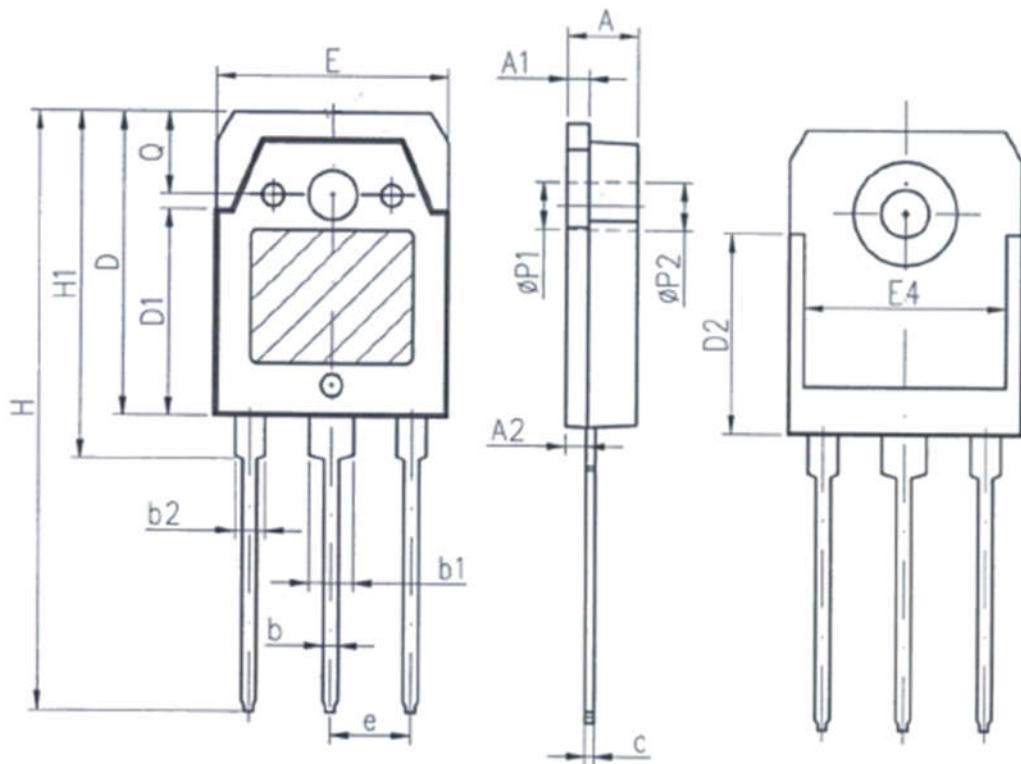


Unit: mm		
Symbol	Min.	Max.
A	4.37	4.77
A1	1.25	1.45
A2	2.20	2.60
b	0.70	0.95
b2	1.17	1.47
c	0.40	0.65
D	15.10	16.10
D1	8.80	9.40
D2	5.50	-

Unit: mm		
Symbol	Min.	Max.
E	9.70	10.30
E3	7.00	-
e	2.54BSC	
e1	5.08BSC	
H1	6.25	6.85
L	12.75	13.80
L1	-	3.40
P	3.40	3.80
Q	2.60	3.00



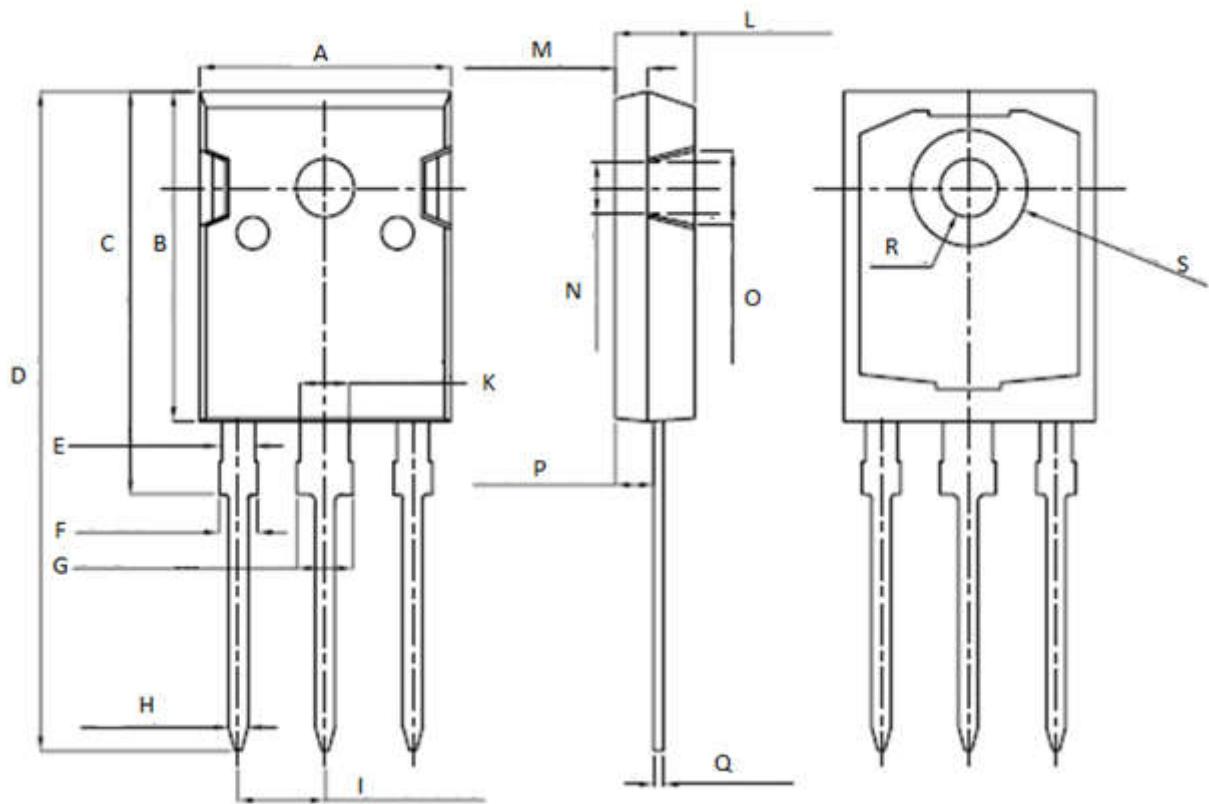
## TO-3PN



Unit : mm		
Symbol	Min.	Max.
A	4.6	5
A1	1.4	1.65
A2	1.18	1.58
b	0.8	1.2
b1	2.8	3.2
b2	1.8	2.2
c	0.5	0.75
D	19.6	20.2
D1	13.55	14.25
D2	12.9REF	
E	15.35	15.85
E4	12.6	-
e	5.45TYP	
H	40.1	40.9
H1	23.15	23.65
P1	3.2REF	
P2	3.5REF	



## TO-247



Unit: mm		
Symbol	Min.	Max.
A	15.95	16.25
B	20.85	21.25
C	20.95	21.35
D	40.5	40.9
E	1.9	2.1
F	2.1	2.25
G	3.1	3.25
H	1.1	1.3
I	5.40	5.50

Unit: mm		
Symbol	Min.	Max.
K	2.90	3.10
L	4.90	5.30
M	1.90	2.10
N	4.50	4.70
O	5.40	5.60
P	2.29	2.49
Q	0.51	0.71
R	Φ 3.5	Φ 3.7
S	Φ 7.1	Φ 7.3



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